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Innodisk Corporate Investor Conference (TPEx: 5289)

Randy Chien, Chairman 2026.11.12-13

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DISCLAIMER

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The viewpoints in this file reflects the company's opinion on the future by the current date. If there are any changes or adjustment in the future, the company is not responsible for notifying the reader or updating the content.

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AGENDA

- Company Profile and Overview
- Market Trend and Product Strategy
- AI in Action Global Campaign
- ESG Commitment
- Financial Information
- Q&A

COMPANY PROFILE & OVERVIEW

CORPORATE OVERVIEW



REVENUE

NT$ 61.51B

(~2026 Q3)

CAPITAL

NT$983M

EPS

NT$256.23

(~2026 Q3)

PATENTS

211

CUSTOMERS

4,000+

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GLOBAL BUSINESS OPERATIONS

California



New Jersey



Netherlands



Beijing



Tokyo



Boston

Texas



France

Germany

Jinan/
Hangzhou/
Suzhou/
Shanghai

Korea

Chengdu

Guangzhou

Taiwan

Vietnam

Shenzhen



Innodisk HQ

/ R&D and Production Center
/ Research Center





Locations	Employees
25	1,259 Taiwan: 1,111 / Overseas: 148

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Lot Size (Sq. Meter)
27,000

Floor Area: 1st building (Sq. Meter)
12,000

Floor Area: 2nd building (Sq. Meter)
15,000

Edge AI System and Solution
Edge AI Embedded Peripheral
Edge AI Camera Module

2026 Capacity (SMT x 6)
1,080K

Maximum Capacity (SMT x 8)
1,440K



YILAN SCIENCE PARK
R&D & MANUFACTURING CENTER



INNODISK HEADQUARTERS

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SPACE

Total :19,800 m²

17F 1,650 m² / Aetina

16F 3,300 m² / R&D Center, Sports & Activity Center, Training Room











7F 3,300 m² / Aetina 660 m²

5F 3,300 m²

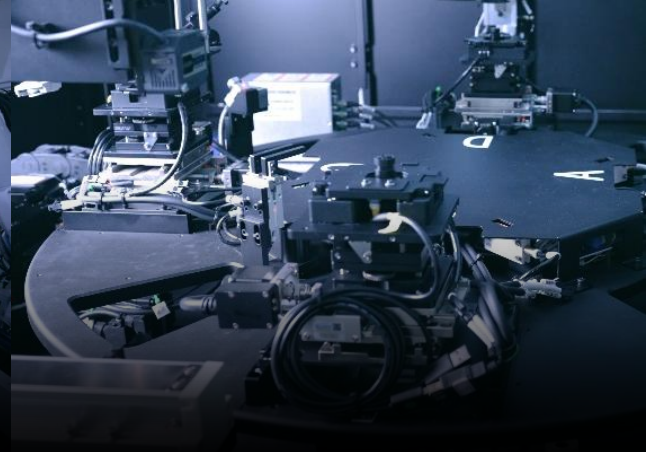
4F 3,300 m²

3F 3,300 m²

2F 1,650 m² / Aetina 660 m²







PRODUCTION	1,440K / Maximum Capacity (SMT x 8)
CERTIFICATIONS	ISO9001 / ISO14001 / ISO45001 / QC080000 / ISO14064-1 / ISO27001 / IEC62443-4-1
MANUFACTURING	New Taipei City / Yilan County



QUALITY & SUSTAINABILITY: OUR TOP PRIORITY

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MARKET TREND & PRODUCT STRATEGY

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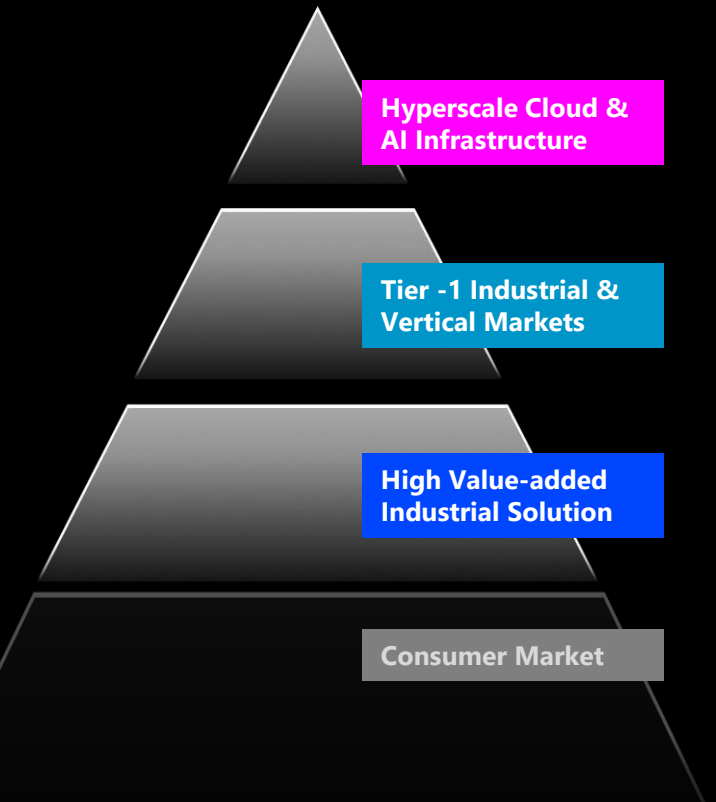
Advancing into High-Value AI Markets



Leading Memory Chip Manufacturers

- HBM, DRAM, NAND Flash

Innodisk's Strategic Focus

High-Value AI & Industrial Applications

- Memory Modules: DDR5, DDR4, CXL
- SSDs: Enterprise Boot Drive, Local Storage
- Edge AI Systems & Edge Servers

Empowering AI Infrastructure & Applications Together

Other Suppliers' Primary Focus

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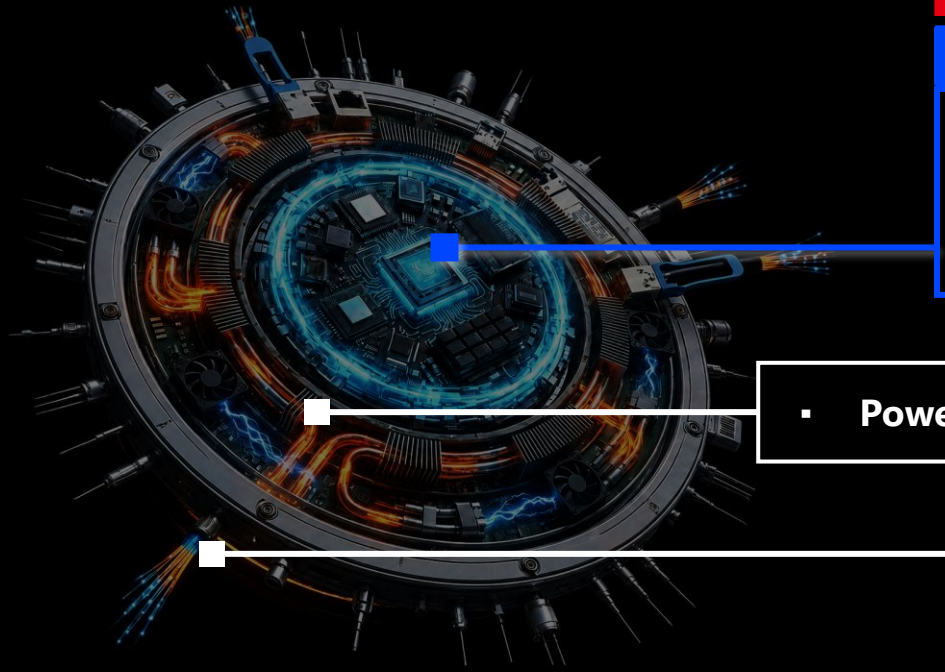
From AI Presence to Market Leadership



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Innodisk Group: Comprehensive AI Core Architecture

- **Compute:** CPU / GPU / NPU / AI ASIC
- **Memory:** DRAM Module
- **Storage:** Flash Storage

- **Power:** Thermal & Energy Management

- **Connectivity:** Optical Communication

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Driving Growth with Confidence

Proven Strengths

- High-End Memory & Storage Solutions
- Proven Edge AI Deployments
- Deep Industrial Market Expertise

Scaling Market Presence

- Data Centers
- Smart NICs & Networking
- Humanoid Robots & Robotics
- Enterprise AI

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Quality & R&D: The Foundation of High-Value AI Growth



Tier-1 Sourced



Chipmaker-Backed



100% Good Die



Industrial-Grade



>50% AI-Focused R&D



20+ Years of Industrial Expertise

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3 CORE VALUES: Market & Product Technology

01
Market & Application Value

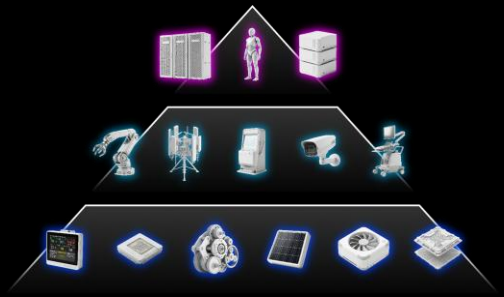
AI redefines value creation across products, services, and operations, driving unprecedented leaps in industry value.

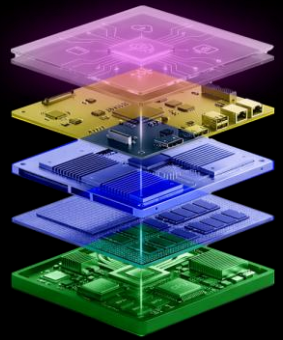
02
Product Technology & Talent Value

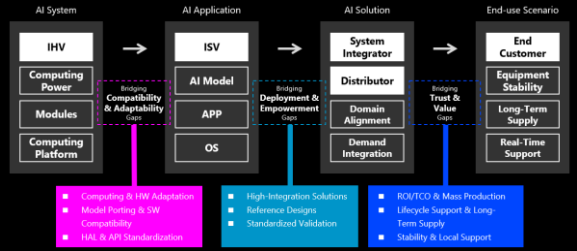
Deploying a robust five-layer AI architecture and expert talent to deliver highly compatible, collaborative solutions for diverse global needs.

03
Edge AI Integration & Deployment Value

Bridging technology gaps with strong R&D capabilities and global partnerships to connect edge applications and accelerate rapid Edge AI deployment.







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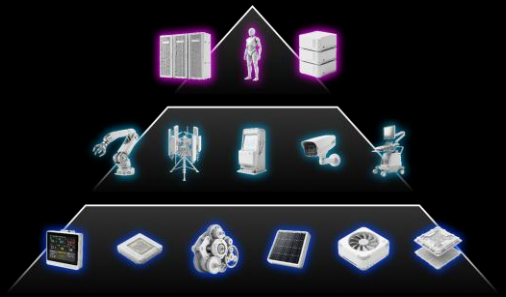

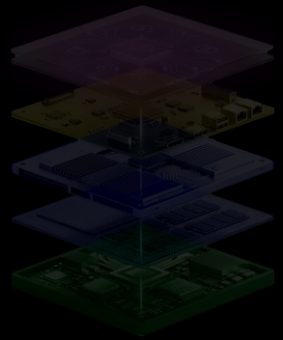

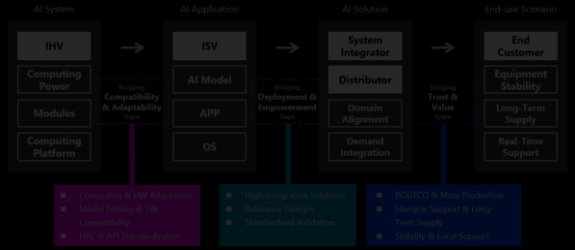

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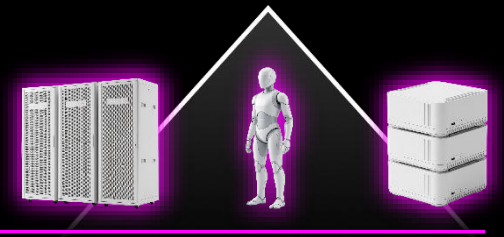
01 Market & Application Value

Hyperscale Cloud & AI Infrastructure

- GPU Server / Networking Switch / Router
- Humanoid Robot / Autonomous



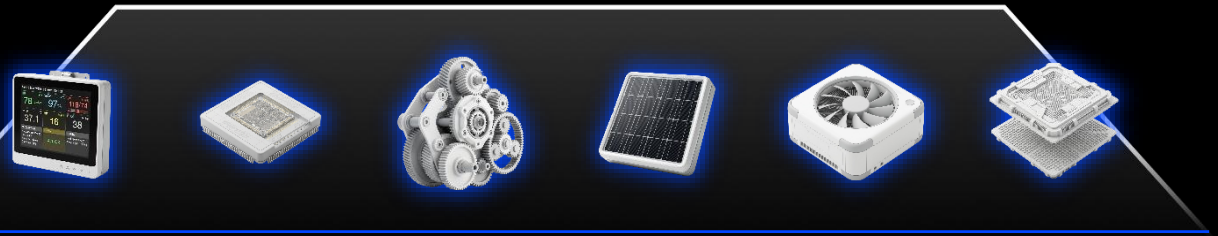
Tier -1 Industrial & Vertical Markets

- Medical / 5G / Surveillance / Entertainment / Automation
- Tier-1 Market Leaders



High Value-added Industrial Solution

- Manufacturing / Retail & Logistic / Smart Energy / Health Care / Communication / Entertainment / Enterprise



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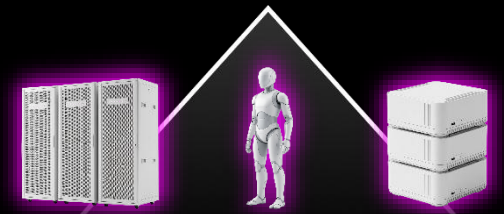
01 Market & Application Value

Hyperscale Cloud & AI Infrastructure



Core Infrastructure for AI Computation, Smart Storage, Transmission, and Scaled Deployment

CSP / Data Center / AI Computing

Expanding AI training and inference fuel exponential growth in demand for high-performance computing, high-bandwidth transmission, and large-scale storage.

Optical & Network Communications

Exploding AI data traffic drives demand for low-latency, high-reliability transmission, backed by robust optical and network infrastructure to support heavy AI workloads.

Robotics & Physical AI

AI is moving from the digital realm to the physical world, empowering robotics and physical AI to integrate into everyday operations through perception, computing, and autonomous decision-making.

Enterprise AI

Enterprises are rapidly adopting generative AI to turn data into business insights while balancing data privacy, governance, and operational efficiency.

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01 Market & Application Value

Tier -1 Industrial & Vertical Markets



Driving Market Standards and Industry Innovation for Scaled Edge AI Deployment

Healthcare

AI accelerates smart diagnostics, treatment, and care to boost precision and efficiency, driving the scaled adoption of advanced medical devices and services.

Networking & Telecom

AI enables real-time network analysis, smart traffic routing, and automated operations to enhance connectivity and power real-time decision-making.

Security & Surveillance

AI vision strengthens real-time recognition, event forecasting, and decision support, shifting security from passive recording to proactive prevention.

Smart Manufacturing

Transitioning from automation to AI-driven manufacturing, leveraging AI vision and robotics to massively boost overall production efficiency.

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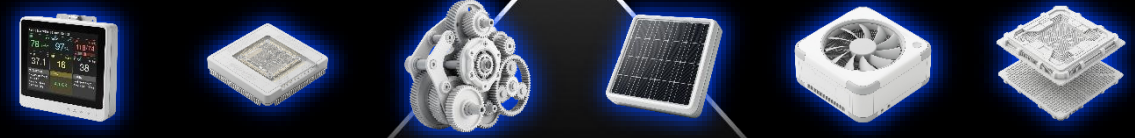
01 Market & Application Value

High Value-added Industrial Solution



Domain Expertise for 4,000+ Global Customers, Accelerating High-Value AI Deployment

Deep Domain Know-How

Complex industrial environments require deep industry insight and application experience to address diverse operational conditions.

High Customization & Integration

Fragmented hardware specs and system architectures demand flexible, tailored hardware-software integration for successful project deployment.

High Value-Added

Growing demand for product differentiation and intelligence makes AI a key driver for equipment upgrades and competitive edge.

Long Lifecycle

Industrial equipment requires rigorous validation and extended lifecycles, demanding uncompromising reliability and supply stability.

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AI redefines value creation across products, services, and operations, driving unprecedented leaps in industry value.

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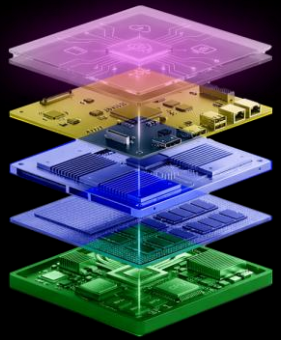

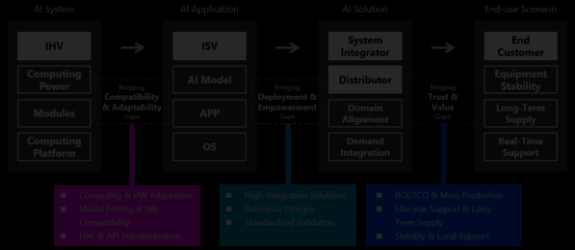

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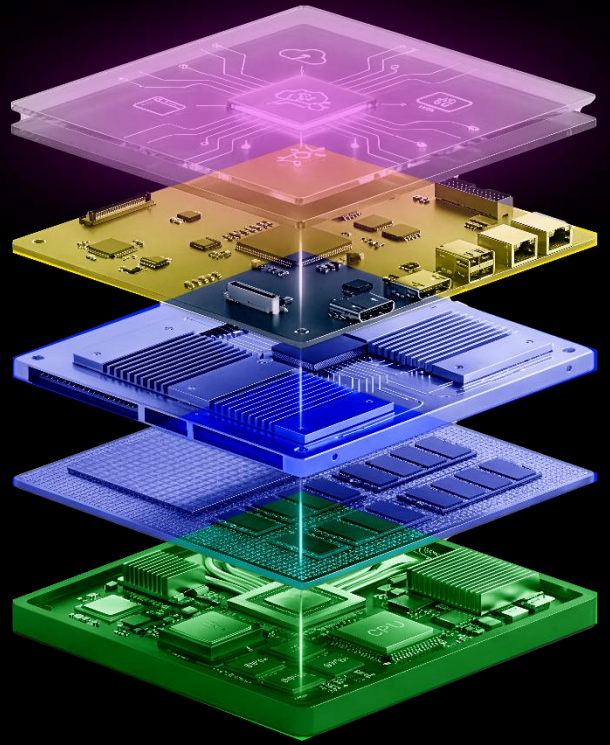
02 Product Technology & Talent Value

- Stack 5: Software
- Stack 4: Sensing & Comm.
- Stack 3: Storage
- Stack 2: Memory
- Stack 1: Compute



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02 Product Technology & Talent Value

Five-Layer Stack × Proprietary Tech Across All Layers

- **Stack 5: Software**
- **Stack 4: Sensing & Comm.**
- **Stack 3: Storage**
- **Stack 2: Memory**
- **Stack 1: Compute**

Heterogeneous Core Computing Power

Reliable platforms, industrial memory and high-end storage

Industrial Module Integration

AI accelerator, network and video capture cards with flexible I/O

Custom System Design

Industrial structure and thermal design to speed up time-to-market

In-House Firmware Value-Add

BIOS / BMC / MCU system-level optimization and customization

Rapid Deployment

End-to-end solutions defined by field needs, solving real pain points

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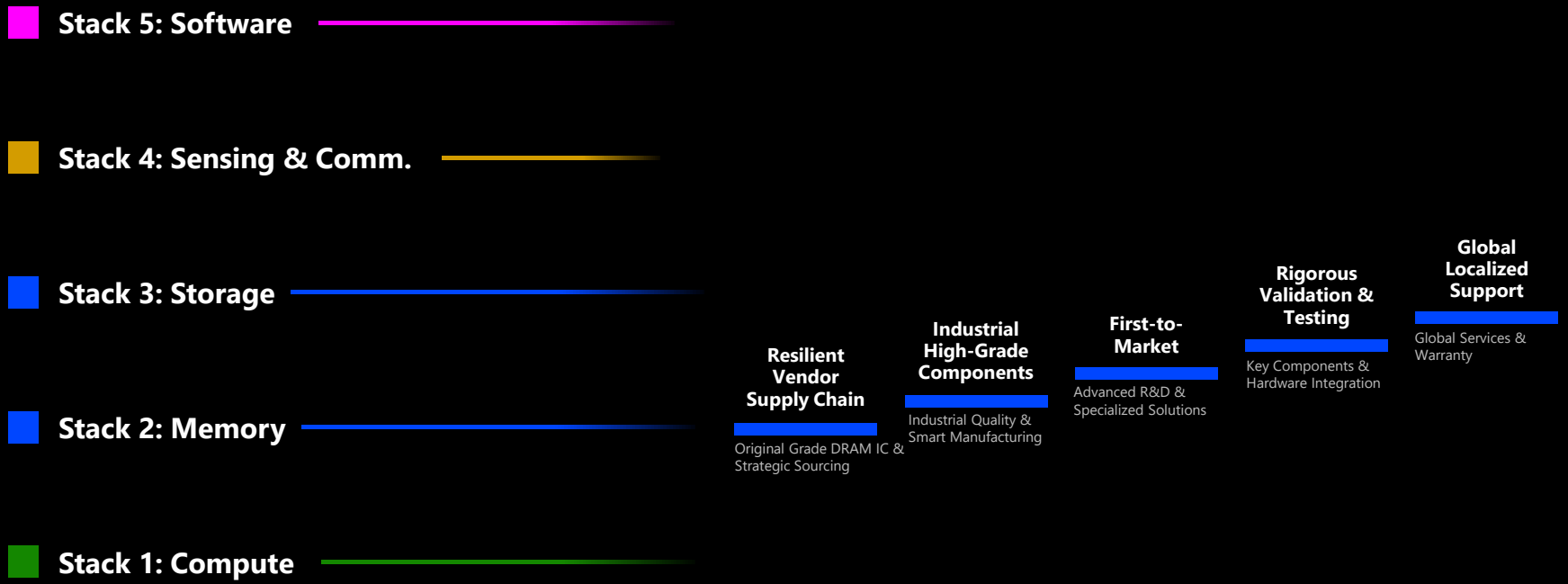
02 Product Technology & Talent Value

Five-Layer Stack × Proprietary Tech Across All Layers



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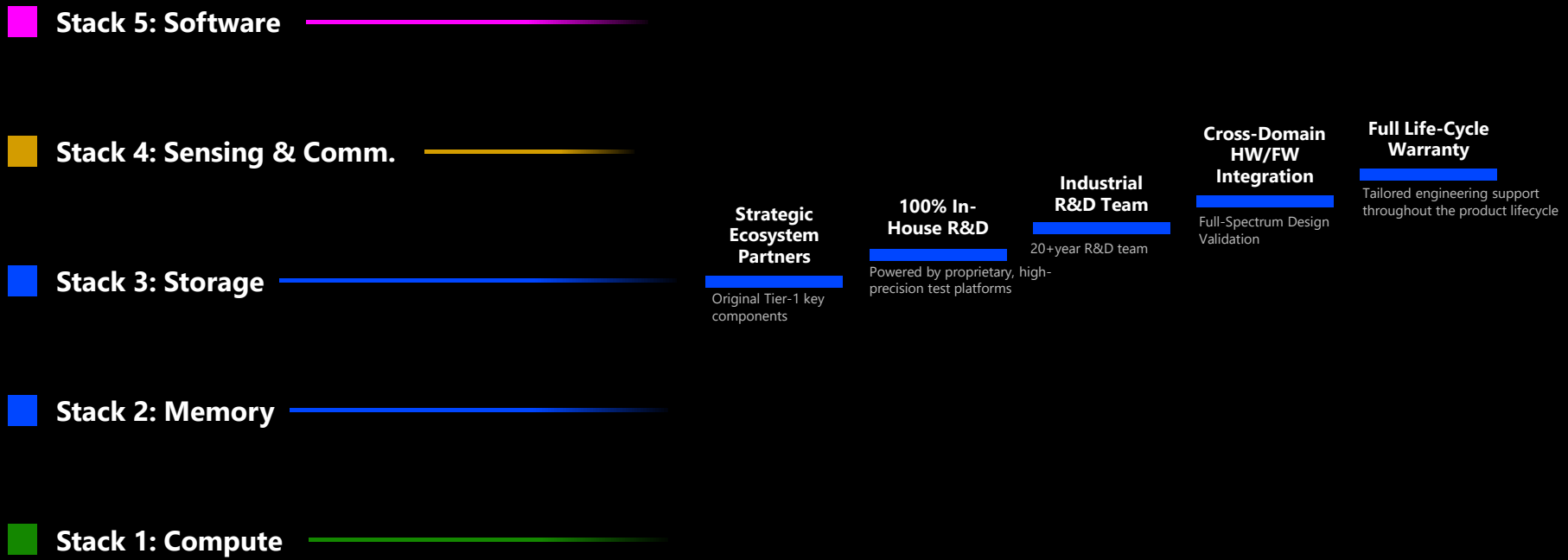
02 Product Technology & Talent Value

Five-Layer Stack × Proprietary Tech Across All Layers



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02 Product Technology & Talent Value

Five-Layer Stack × Proprietary Tech Across All Layers

- **Stack 5: Software**
- **Stack 4: Sensing & Comm.**
- **Stack 3: Storage**
- **Stack 2: Memory**
- **Stack 1: Compute**

Cross-Platform Design
X86, Nvidia, Qualcomm, AI ASIC

In-House Driver / FW
Easy to integrate with hardware and software

High-Speed Transmission & Smart Connectivity
AI connectivity and data transmission

Custom Sensor Solutions
In house R&D customization

Multi-Interface & Multi-Form-Factor Design
LAN, Optical, Series, CAN, EtherCAT with PCIe,M.2 FF

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02 Product Technology & Talent Value

Five-Layer Stack × Proprietary Tech Across All Layers

Stack 5: Software

- **Cloud Device Management** — iCAP, OTA, OOB remote management
- **API / SDK Support** — Friendly Utility Support
- **BIOS / BSP / Driver Customization** — In-house R&D support customization
- **Model Inference & Training Tools** — iVIT-T & iVIT-I Tool Kits
- **AI Engine** — MCP protocol expedite Agentic AI

Stack 4: Sensing & Comm.

Stack 3: Storage

Stack 2: Memory

Stack 1: Compute

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02 Product Technology & Talent Value

Five-Layer Stack × Proprietary Tech Across All Layers

- **Stack 5: Software**
- **Stack 4: Sensing & Comm.**
- **Stack 3: Storage**
- **Stack 2: Memory**
- **Stack 1: Compute**

Cloud Device Management
iCAP, OTA, OOB remote management

Cross-Platform Design
X86, Nvidia, Qualcomm, AI ASIC

Strategic Ecosystem Partners
Original Tier-1 key components

Resilient Vendor Supply Chain
Original Grade DRAM IC & Strategic Sourcing

Heterogeneous Core Computing Power
Reliable platforms, industrial memory and high-end storage

API / SDK Support
Friendly Utility Support

In-House Driver / FW
Easy to integrate with hardware and software

100% In-House R&D
Powered by proprietary, high-precision test platforms

Industrial High-Grade Components
Industrial Quality & Smart Manufacturing

Industrial Module Integration
AI accelerator, network and video capture cards with flexible I/O

BIOS / BSP / Driver Customization
In-house R&D support customization

High-Speed Transmission & Smart Connectivity
AI connectivity and data transmission

Industrial R&D Team
20+year R&D team

First-to-Market
Advanced R&D & Specialized Solutions

Custom System Design
Industrial structure and thermal design to speed up time-to-market

Model Inference & Training Tools
iVIT-T & iVIT-I Tool Kits

Custom Sensor Solutions
In house R&D customization

Cross-Domain HW/FW Integration
Full-Spectrum Design Validation

Rigorous Validation & Testing
Key Components & Hardware Integration

In-House Firmware Value-Add
BIOS / BMC / MCU system-level optimization and customization

AI Engine
MCP protocol expedite Agentic AI

Multi-Interface & Multi-Form-Factor Design
LAN, Optical, Series, CAN, EtherCAT with PCIe,M.2 FF

Full Life-Cycle Warranty
Tailored engineering support throughout the product lifecycle

Global Localized Support
Global Services & Warranty

Rapid Deployment
End-to-end solutions defined by field needs, solving real pain points

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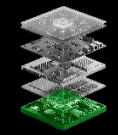
Stack 1: Compute



Powered by NVIDIA Qualcomm Intel



APEX-S100



APEX-X100



APEX-P100



AIB-AT78/68



APEX-X200



APEX-X100-Q



APEX-P300



AIE-PX11/12/21/22



APEX-P200



APEX-E300



APEX-A100



APEX-E100

10,000 TOPS

1,000 TOPS

100 TOPS

(TOPS @ INT8)

Enterprise AI Computing

- Enterprise AI Platform
- Multi-Agent AI Collab.
- RAG
- Fine-Tuning
- 70B+ LLM Deployment

High-Performance Edge AI Inference

- Multi-Camera AOI
- Defect Inspection
- Machine Vision
- Medical Imaging
- Agentic AI

Vision AI & Edge Analytics

- Surveillance Video Analysis
- Smart Retail
- AOI
- Crowd / Traffic Analysis
- AMR

Edge Device AI Inference

- Image Classification
- Facial Recognition
- OCR
- License Plate Recognition (LPR)
- Single-Object Detection

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Stack 2 & 3: Memory & Storage

INDUSTRIAL EDGE AI

Industrial Vertical Market

On-device SSD



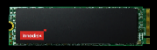
DDR5 ECC SODIMM /
DDR5 ECC UDIMM / DDR5 RDIMM



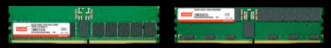
ENTERPRISE EDGE AI

Enterprise Private
AI Server

On-prem Edge AI /
KV Cache SSD



DDR5 RDIMM /
DDR5 MRDIMM



AI Inference

ENTERPRISE EDGE AI

AI Server / CSP

Central Cloud
Data Center SSD



CXL Memory Module /
CXL AIC / DDR5 MRDIMM



AI Training

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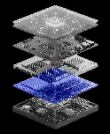
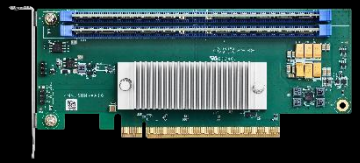
Stack 2: Memory



BREAKING AI ARCHITECTURE BOTTLENECKS

CXL AIC (ADD-IN-CARD) Breaking Edge Computing's Memory Barrier



- **Objective:** Expand memory capacity for the next-gen AI.
- **Key Feature:** Seamless, large-scale memory scaling.
- **Benefit:** Optimized TCO for Hyperscale Data Centers & AI Training.

EMPOWERING EDGE AI COMPUTING

DDR5 8000MT/s RDIMM Edge AI Ultra-High-Speed Computing Engine



- **Target:** Edge AI & high-speed networking bandwidth.
- **Performance:** Ultra-low latency & superior stability.
- **Application:** Real-time edge inference & massive data processing.

DRAM Module Portfolio

AI Memory



Embedded Memory



Server Memory



Wide Temp. Memory



Customized Memory



- **Formfactor:**
  CAMM2 / CUDIMM / CSODIMM / SODIMM / RDIMM / VLP / .....
- **Technology & Generation:**
  CXL / DDR5 / DDR4 / DDR3 / DDR2

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Stack 3: Storage

PCIe Gen5 & 218-layer 3D NAND Flash

MAXIMIZING SYSTEM BOOT RELIABILITY

DATACENTER SSD | BOOT DRIVE

PCIe Gen5, 5TS4-P Series: E1.S and U.2



- **Optimized Booting:** High-speed startup and OS loading.
- **Reliability:** High endurance for frequent write cycles.

ACCELERATING LARGE-SCALE DATA THROUGHPUT

DATACENTER SSD | STORAGE DRIVE

PCIe Gen5, 5TS-P Serries: U.2, EDSFF (E3.S, E3.L and E1.S)



- **High Throughput:** Designed for large-scale data handling and sustained performance.
- **Low Latency:** Scalable for heavy processing and storage.

Flash Storage (SSD) Portfolio

PCIe



SD



SATA



USB



PATA



- **Embedded Product Line:**
  M.2 / U.2 / CFexpress / EDSFF / 2.5" / 1.8" / SATA Slim / SATADOM / mSATA / CFast / nanoSSD /CompactFlash Card / SD Card & MicroSD Card / USB / USB EDC

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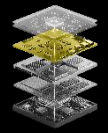
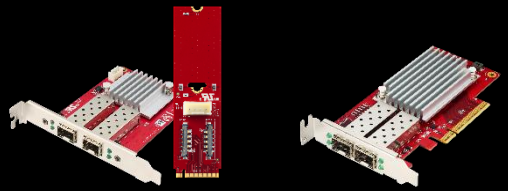
Stack 4: Sensing & Comm.



REVOLUTIONIZING COMPACT SYSTEM BOOTING

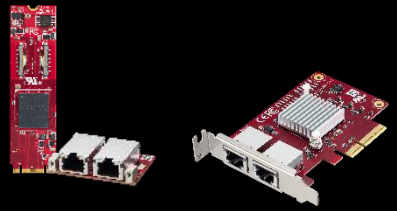
10GbE / 25GbE OPTICAL LAN MODULES



- **Space-Efficient:** World's First M.2 Optical LAN Module Family for compact systems.
- **High-Speed Transfer:** Fast, stable data transfer for higher throughput.

ENHANCING HIGH-EFFICIENCY DATA EXCHANGE

10GBE RJ45 LAN MODULE



- **Industrial-Grade:** World's First Industrial-Grade 10GbE LAN Module.
- **Low-Latency:** Real-time data transfer for high-performance applications.

Intelligent Peripheral Solution Portfolio

LAN



CAN Bus & CAN FD



Serial



Wi-Fi



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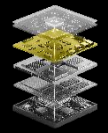
Stack 4: Sensing & Comm.



RUGGEDIZED LONG-RANGE VISION & CLARITY

GMSL2 CAMERA SERIES

High-bandwidth, long-range, and low-latency transmission

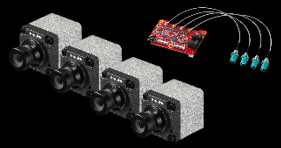


- **IP67/IP69K Ruggedized:** Maximum dust, water proof.
- **15m Long-Reach:** Stable performance over extended distances.
- **On-board ISP:** Superior image quality and professional control.
- **NVIDIA Jetson & Raspberry Pi Ready:** Support for leading AI platforms.

REDEFINING THE EDGE AI VISION STANDARD

INNODISK VISION SOLUTION: BUNDLE PACKAGE

Seamless Integration. Rapid Deployment.
Proven Performance



- **Unified Hardware Bundle:** Pairs GMSL2 camera and capture card for seamless evaluation.
- **Seamless Integration:** Pre-validated design eliminates compatibility friction.
- **Accelerated Development:** Focus directly on vision software and rapid deployment.
- **Superior Performance:** Delivers sharp image quality and stable GMSL2 signal integrity.

Camera Module Portfolio

USB 2.0



MIPI CSI-2



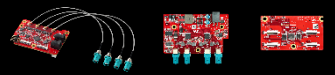
GMSL2



MIPI over Type-C



Capture Card



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Stack 5: Software

INNOVATING IN SOFTWARE. ELEVATING VALUE AT THE EDGE.

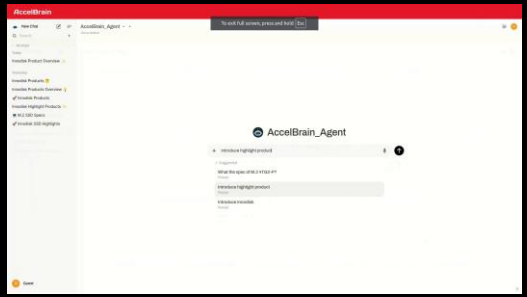
Retail Intelligence | Surveillance Intelligence | Enterprise & Building Intelligence | Industrial Automation Intelligence

Business Logic Layer: iCAP | iVIT | innoPPE | AccelBrain

Service Communication Layer: HTTP | MQTT | CoAP | MCP

Host

- **Service API Endpoint Layer**: Device Management | AI Engine | Multi-Streaming
- **Agentic AI Layer**: MCP Server
- **Platform Empowerment Layer**: OS Building | BSP | Driver
- **HW Module Adapter Layer**: eAPI | CANBus Utility | SSD SMART Utility | SPD Code R/W





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3 CORE VALUES: Market & Product Technology

01
Market & Application Value

AI redefines value creation across products, services, and operations, driving unprecedented leaps in industry value.

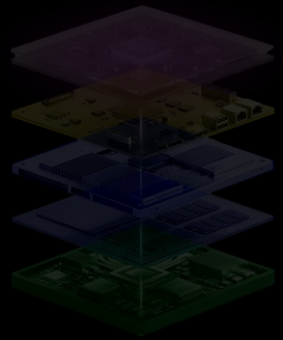
02
Product Technology & Talent Value

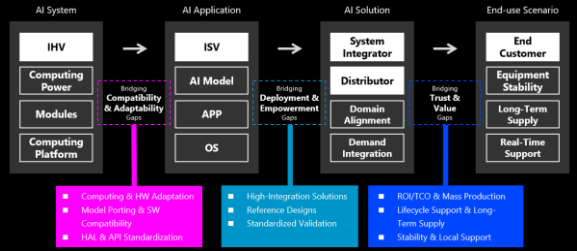
Deploying a robust five-layer AI architecture and expert talent to deliver highly compatible, collaborative solutions for diverse global needs.

03
Edge AI Integration & Deployment Value

Bridging technology gaps with strong R&D capabilities and global partnerships to connect edge applications and accelerate rapid Edge AI deployment.







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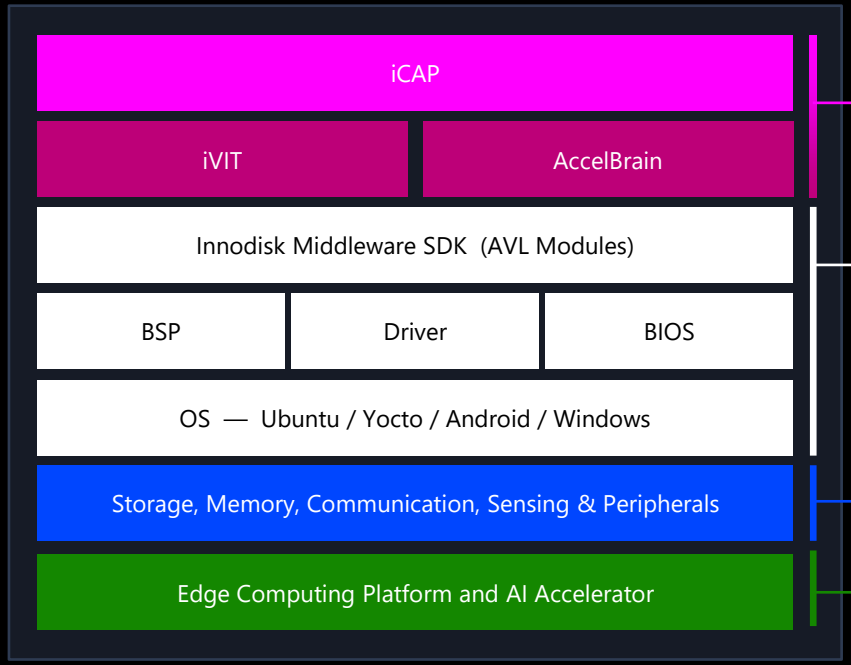
03 Edge AI Integration & Deployment Value

Bridging Tech Gaps to Minimize Client Integration Effort



Cross-Stack Software Architecture

Self-developed cross-stack architecture integrating OS, BSP, drivers, BIOS, middleware, utilities, AI models, and applications for zero porting effort, high integration, and fast deployment.

Original Silicon Vendor Support & Complete Product Portfolio

Partner with global leading storage and memory IC vendors to provide a complete portfolio covering data sensing, storage, computing, transfer, and applications.

World-Class Design & Manufacturing

- Intel: Reference Kit / Customer Reference Design
- NVIDIA: Elite Partner / MGX Partner (Aetina)
- Qualcomm: IoT Partner / On-Premise Partner
- Global AI ASIC: Design & Manufacturing Services

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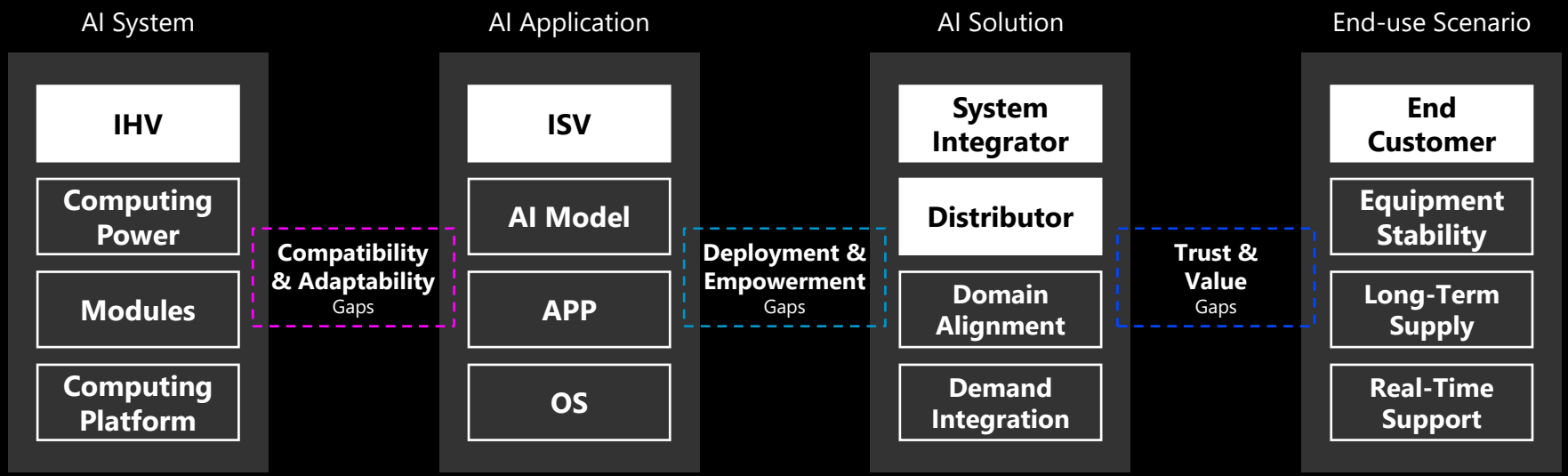
03 Edge AI Integration & Deployment Value

Bridging Tech Gaps to Minimize Client Integration Effort



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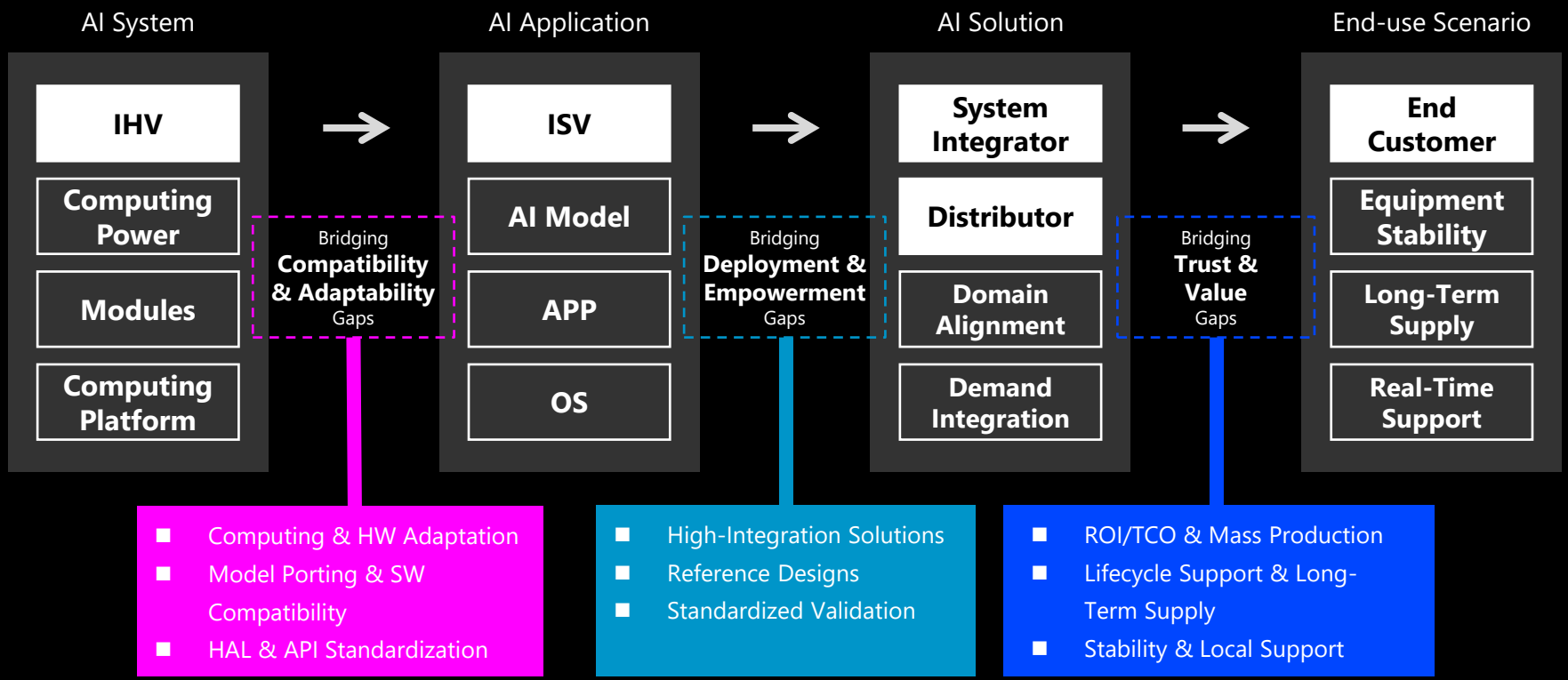
03 Edge AI Integration & Deployment Value

Bridging Tech Gaps to Minimize Client Integration Effort



INNODISK EDGE AI BUILDING BLOCKS

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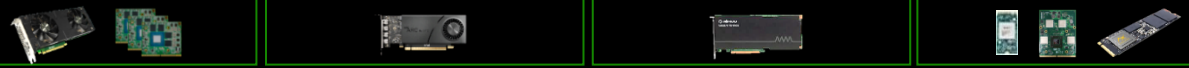
SOFTWARE / FIRMWARE

Cloud AI Platform	iCAP
AI-Stack SDK	AccelBrain, AccelTune, IQ Studio, iVIT
Software Tools	iSeries Software
OS & Middleware	Windows, Linux, BSP, eAPI, Drivers

AI ACCELERATOR

NVIDIA | Intel | Qualcomm | AI ASIC



AI PLATFORM

x86

Intel Atom x6000 / 7000 | Intel 12 / 13 / 14th Gen Core-i | Intel Core Ultra Series1 / 2 / 3 | Intel Xeon 6

ARM

NVIDIA Jetson Orin / Thor | Qualcomm Dragonwing IQ 9 / 8 / X | NXP i.MX 8M Plus / 95

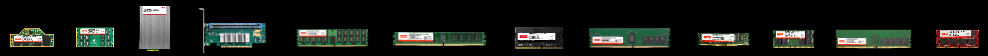


AI Storage / Memory

Flash



DRAM



AI Peripheral

Camera



LAN



Display



Air Sensor / Gas Sensor



Wireless



Storage



CAN Bus / CAN FD



Serial



Device Management
Monitoring / OTA / Diagnostics

Inference & Tuning
Model Deployment / Training / Optimization

Runtime & System Support

OS Porting / Runtime Support / Pre-Configured System / eAPI Hardware Control / Software Configuration

Data Management

Firmware Customization / Health Monitoring / Encryption & RAID

Sensing & Communication

Vision Input / Transmission / Real-Time Control

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Market & Application Value

Hyperscale Cloud & AI Infrastructure

- GPU Server / Networking Switch / Router
- Humanoid Robot / Autonomous



Exponential Growth

Tier -1 Industrial & Vertical Markets

- Medical / 5G / Surveillance / Entertainment / Automation
- Tier-1 Market Leaders



Global Market Leader

High Value-added Industrial Solution

- Manufacturing / Retail & Logistic / Smart Energy / Health Care / Communication / Entertainment / Enterprise



4,000+ High-value Customer Base


Phase 3
2026 Q4 (Scheduled to Break Ground)
Phase 2
2024 (In Operation)
Phase 1
2018 (In Operation)
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Innodisk R&D and Production Center
Construction of Phase 3 Building and Dormitory


Innodisk R&D & Manufacturing center
Construction of Phase 3 Building and Dormitory
Scheduled to Break Ground in 2026 Q4
Phase 3
Phase 2
Phase 1
innodisk


Phase 3
Phase 2
Phase 1
Dormitory


Phase 3
Dormitory
Phase 1



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AI IN ACTION GLOBAL CAMPAIGN

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COMPUTEX 2026

@TAIWAN, TAIPEI















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INNODISK AI IN ACTION

Promote AI solutions with global partners



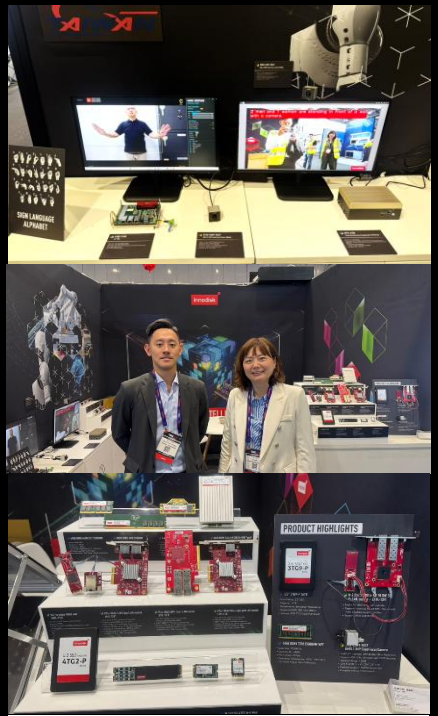
AI EXPO @Taiwan



IT Week @Japan



Automate @USA



Hardware Pioneer Max @United Kindom

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ESG COMMITMENT

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ACHEIVEMENTS & HIGHLIGHTS

- Maintaining a Corporate Governance Evaluation between **6% to 20%.**
- Approved by the Board of Directors, the company has set its Net Zero Emission Pathway, marking a proactive step toward long-term net-zero transition.
- Established the **"Sustainability Development & Information Security Committee"** to enhance ESG commitment.
- Received the EcoVadis Bronze Medal, CommonWealth Sustainability Awards, and the Parenting Family-Friendly Workplace Award, reflecting Innodisk's well-rounded achievements in sustainability.

ECOLOGICAL HARMONY

Wuweigang Waterbird reserve: Biodiversity Three-Year Project

- Partner with local organizations on habitat protection, invasive species removal, and little tern conservation.
- Advance ecological monitoring and environmental education to foster a thriving, biodiverse ecosystem with stakeholders.

Yue-Ming School: Three-Year Ocean Activists Program

- Connect academia and local communities to cultivate future ocean advocates and strengthen social impact.
- Build sustainability awareness through school-based conservation workshops and projects.







宜鼎國際 永續之路

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FINANCIAL INFORMATION

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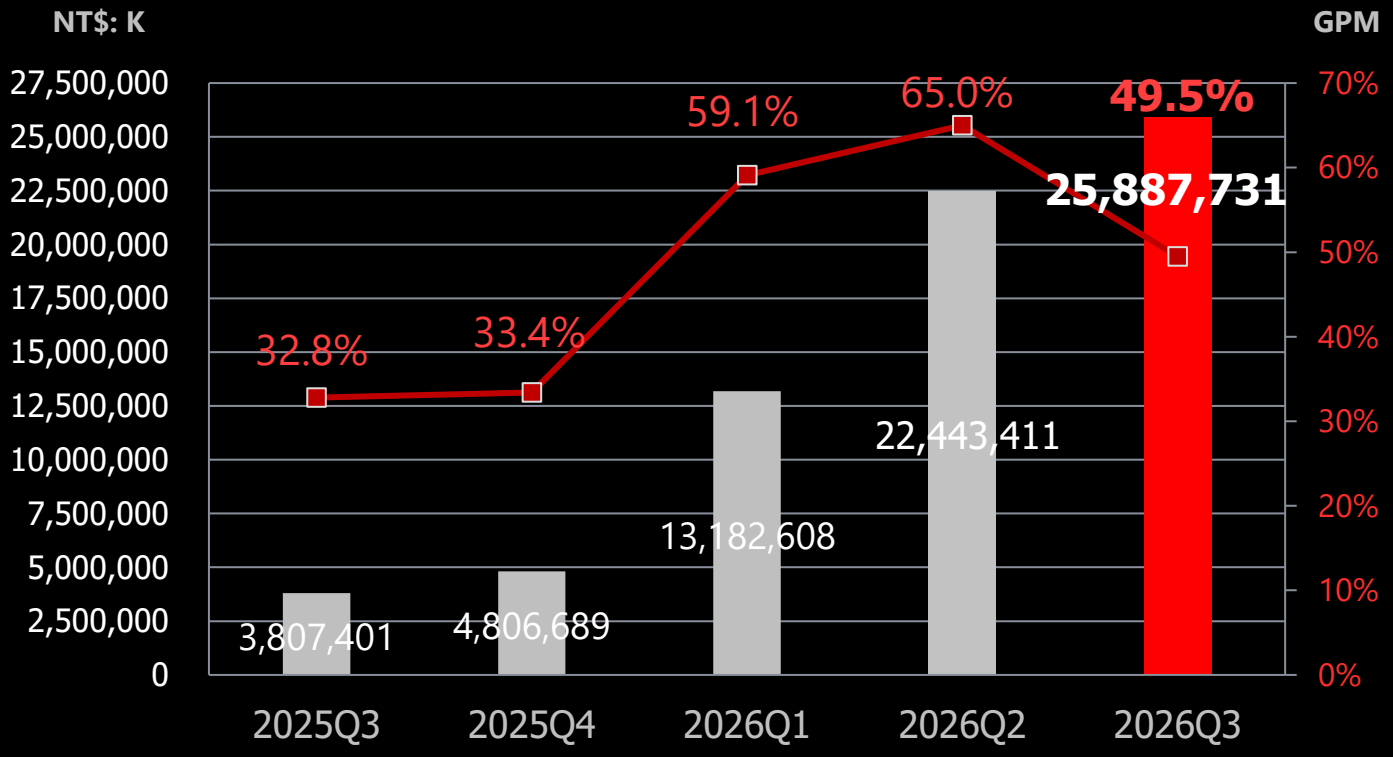
Revenues and GPM over last 5 quarters



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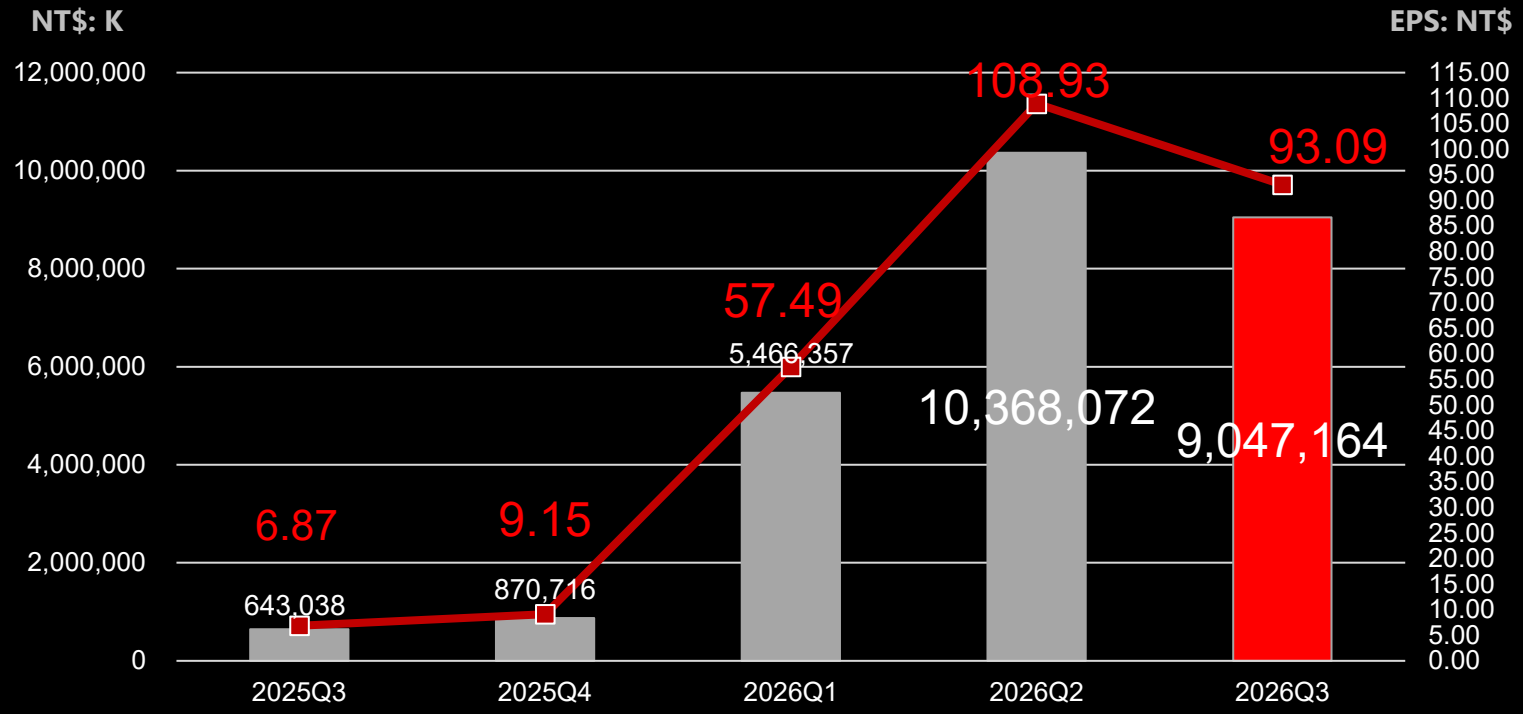
Net Profits and EPS over last 5 quarters



Note: Quarterly EPS is calculated based on the weighted average share capital outstanding for the quarter.

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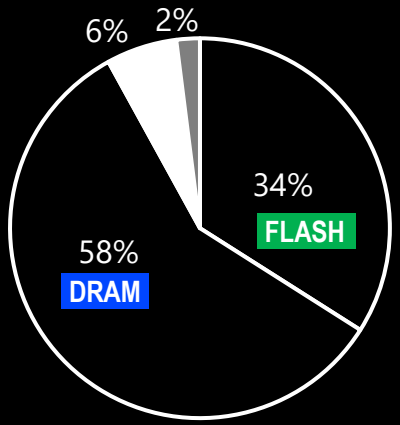
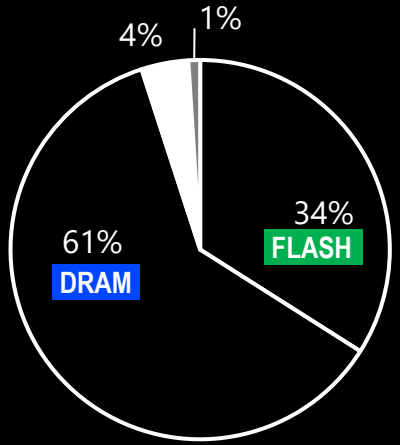
Revenue Breakdown by Product Lines

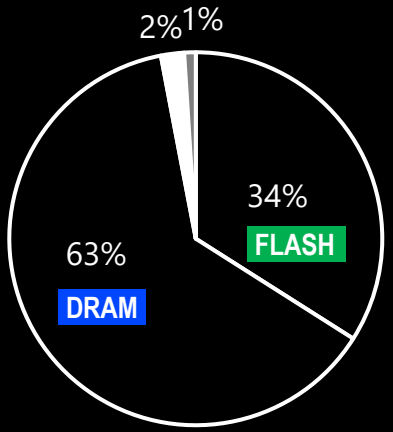
2025Q3



2026Q2



2026Q3



DRAM FLASH AI Solutions Others

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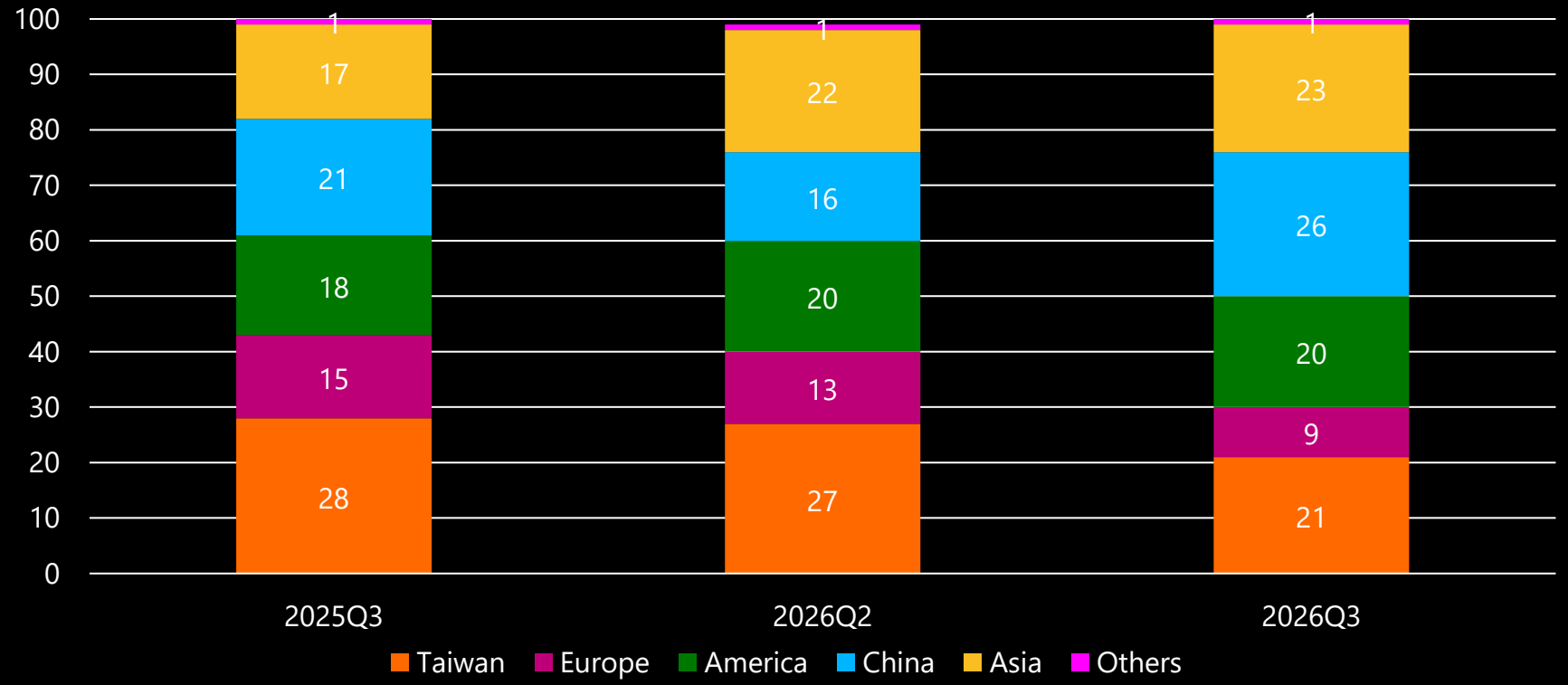
Revenue Breakdown by Regions



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2026Q3 Operating Results

	2026Q3	2026Q2	QoQ	2025Q3	YoY
Revenues	**25,887,731**	**22,443,411**	**15.3%**	**3,807,401**	**579.9%**
Cost of good sold	13,080,680	7,853,799	66.6%	2,558,583	411.2%
Gross profit	**12,807,051**	**14,589,612**	**-12.2%**	**1,248,818**	**925.5%**
Operation expenses	1,452,136	1,443,892	0.6%	531,059	173.4%
Operation profits	**11,354,915**	**13,145,720**	**-13.6%**	**717,759**	**1482.0%**
Non-operating income and expenses	100,706	68,664	46.7%	88,738	13.5%
Profit before tax	**11,455,621**	**13,214,384**	**-13.3%**	**806,497**	**1320.4%**
Income tax expense	2,390,827	2,808,521	-14.9%	163,923	1358.5%
Net profits	**9,064,794**	**10,405,863**	**-12.9%**	**642,574**	**1310.7%**
Non-controlling interests	17,630	37,791	-53.3%	-464	-3899.6%
Net profit attributable to parent company	**9,047,164**	**10,368,072**	**-12.7%**	**643,038**	**1306.9%**
EPS	93.09	108.93		6.87	
Gross margin	49.5%	65.0%		32.8%	
Operating margin	43.9%	58.6%		18.9%	
Net profit rate	35.0%	46.4%		16.9%	

Note: Quarterly EPS is calculated based on the weighted average share capital outstanding for the quarter.

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Q&A

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ARCHITECT INTELLIGENCE